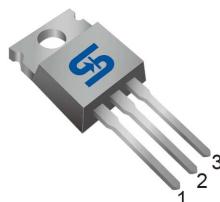
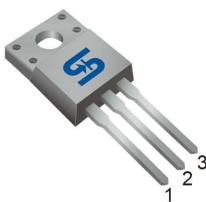


TO-220

ITO-220

Pin Definition:

1. Gate
2. Drain
3. Source

PRODUCT SUMMARY

V_{DS} (V)	R_{DS(on)}(Ω)	I_D (A)
500	0.48 @ V _{GS} =10V	13

General Description

The TSM13N50 N-Channel enhancement mode Power MOSFET is produced by planar stripe DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply, power factor correction, electronic lamp ballast based on half bridge.

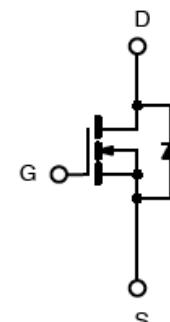
Features

- Low R_{DS(ON)} 0.38Ω (Typ.)
- Low gate charge typical @ 36nC (Typ.)
- Low Crss typical @ 7.7pF (Typ.)
- Fast Switching

Ordering Information

Part No.	Package	Packing
TSM13N50CZ C0	TO-220	50pcs / Tube
TSM13N50CI C0	ITO-220	50pcs / Tube

Block Diagram


N-Channel MOSFET

Absolute Maximum Rating (Ta = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	500	V
Gate-Source Voltage	V _{GS}	±30	V
Continuous Drain Current(T _C =25°C)	I _D	13	A
Pulsed Drain Current *	I _{DM}	52	A
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5	V/ns
Single Pulse Avalanche Energy (Note 2)	E _{AS}	563	mJ
Avalanche Current (Repetitive) (Note 1)	I _{AR}	13	A
Repetitive Avalanche Energy (Note 1)	E _{AR}	18.3	mJ
Operating Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

* Limited by maximum junction temperature

Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance - Junction to Case	R _{θ_{JC}}	0.63	°C/W
		2.4	
Thermal Resistance - Junction to Ambient	R _{θ_{JA}}	62.5	

Notes: Surface mounted on FR4 board t ≤ 10sec

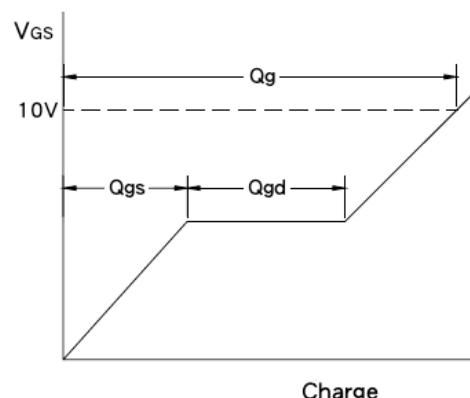
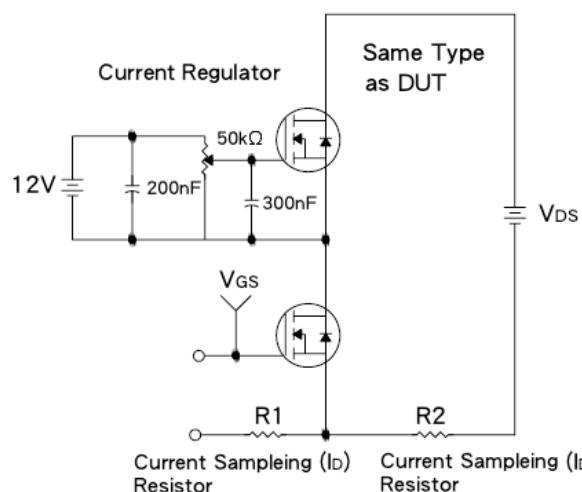
Electrical Specifications ($T_a = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	BV_{DSS}	500	--	--	V
Drain-Source On-State Resistance	$V_{GS} = 10\text{V}, I_D = 6.5\text{A}$	$R_{DS(\text{ON})}$	--	0.38	0.48	Ω
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	$V_{GS(\text{TH})}$	2.0	--	4.0	V
Zero Gate Voltage Drain Current	$V_{DS} = 500\text{V}, V_{GS} = 0\text{V}$	I_{DSS}	--	--	1	μA
Gate Body Leakage	$V_{GS} = \pm 30\text{V}, V_{DS} = 0\text{V}$	I_{GSS}	--	--	± 100	nA
Forward Transconductance	$V_{DS} = 30\text{V}, I_D = 6.5\text{A}$	g_{fs}	--	14	--	S
Diode Forward Voltage	$I_S = 13\text{A}, V_{GS} = 0\text{V}$	V_{SD}	--	--	1.5	V
Dynamic						
Total Gate Charge	$V_{DS} = 400\text{V}, I_D = 13\text{A}, V_{GS} = 10\text{V}$	Q_g	--	36	--	nC
Gate-Source Charge		Q_{gs}	--	8.5	--	
Gate-Drain Charge		Q_{gd}	--	8.7	--	
Input Capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	C_{iss}	--	1918	--	pF
Output Capacitance		C_{oss}	--	187	--	
Reverse Transfer Capacitance		C_{rss}	--	7.7	--	
Switching						
Turn-On Delay Time	$V_{DD} = 250\text{V}, I_D = 13\text{A}, R_G = 25\Omega$	$t_{d(on)}$	--	53	--	nS
Turn-On Rise Time		t_r	--	45	--	
Turn-Off Delay Time		$t_{d(off)}$	--	156	--	
Turn-Off Fall Time		t_f	--	59	--	
Reverse Recovery Time	$V_{GS} = 0\text{V}, I_S = 13\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	t_{fr}	--	325	--	nS
Reverse Recovery Charge		Q_{fr}	--	3.3	--	uC

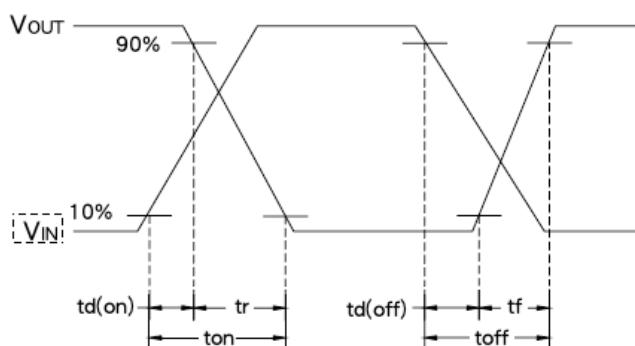
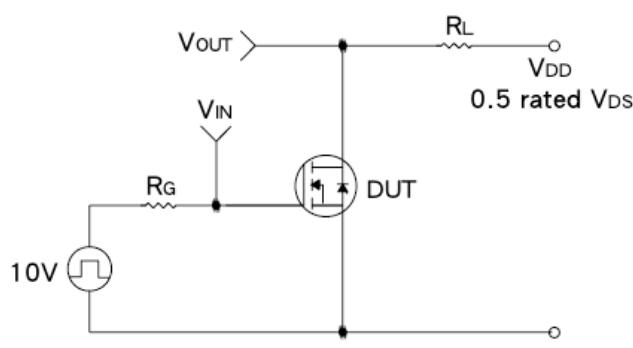
Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. $V_{DD} = 50\text{V}, I_{AS}=13\text{A}, L=6\text{mH}, R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$
3. $I_{SD} \leq 13\text{A}, di/dt \leq 200\text{A}/\mu\text{s}, V_{dd} \leq BV_{DS}$, Starting $T_J=25^\circ\text{C}$
4. Pulse test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
5. b For design reference only, not subject to production testing.
6. c Switching time is essentially independent of operating temperature.

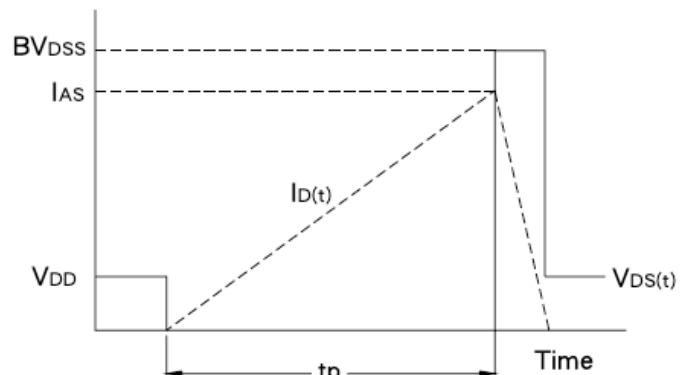
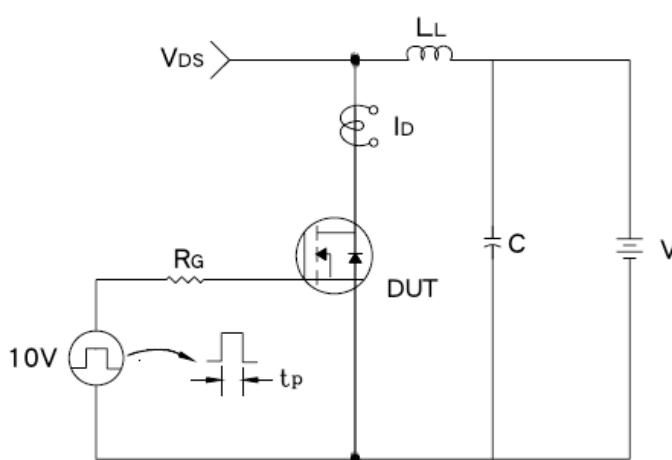
Gate Charge Test Circuit & Waveform



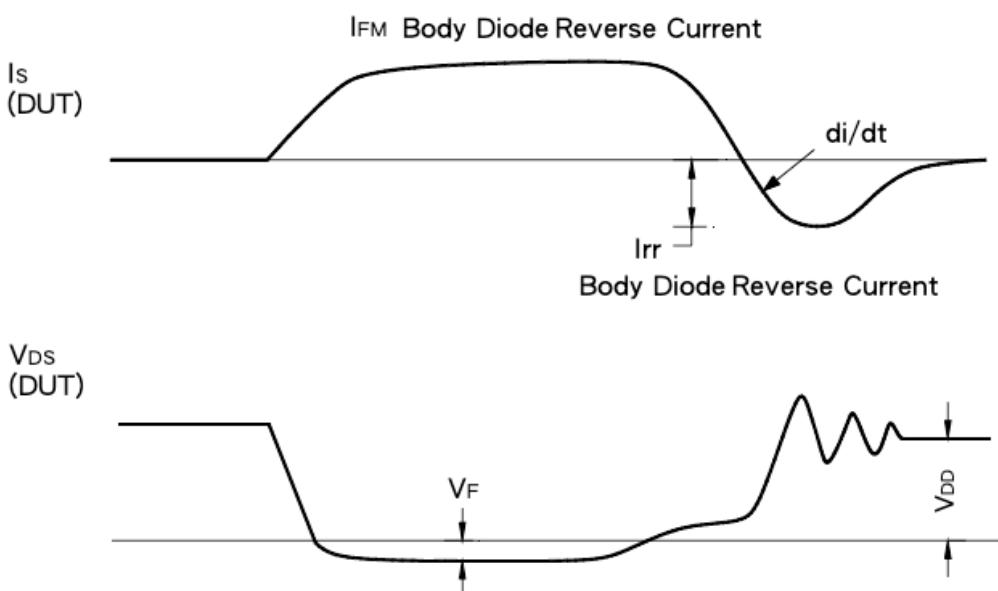
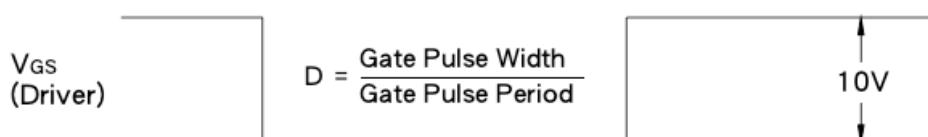
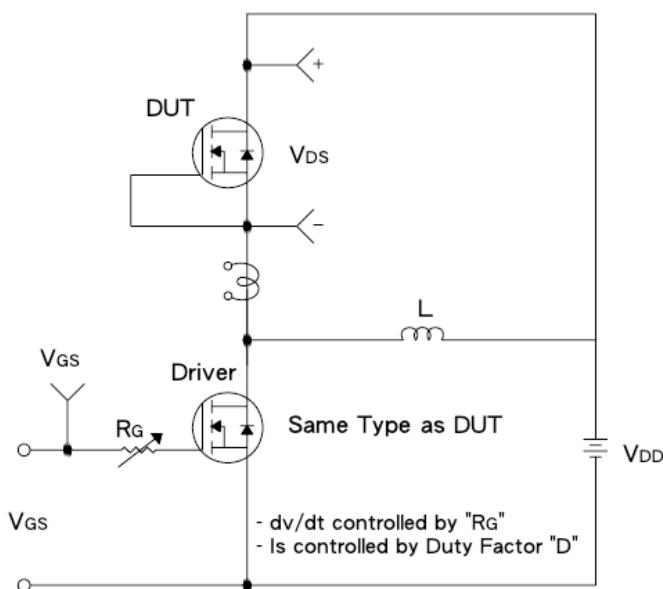
Resistive Switching Test Circuit & Waveform



E_{AS} Test Circuit & Waveform

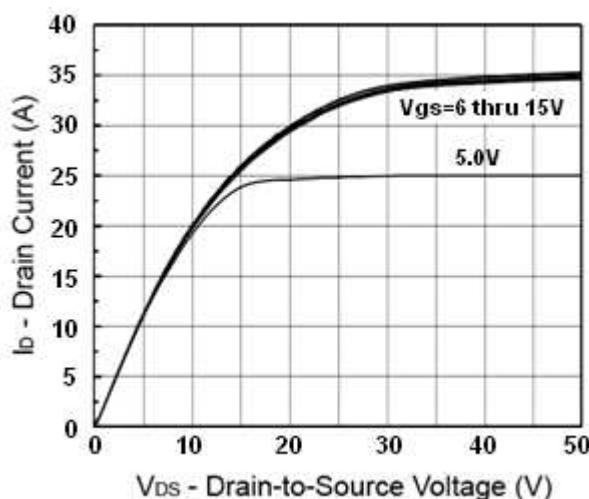


Diode Reverse Recovery Time Test Circuit & Waveform

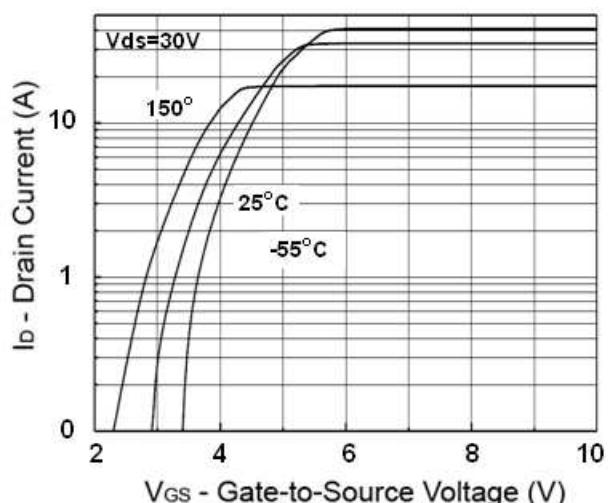


Electrical Characteristics Curve ($T_c = 25^\circ\text{C}$, unless otherwise noted)

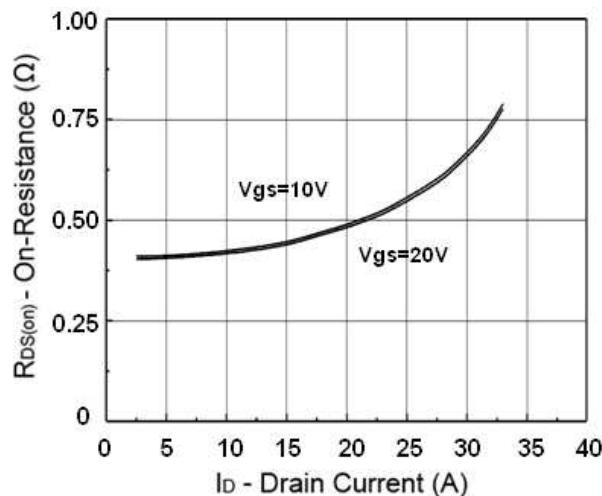
Output Characteristics



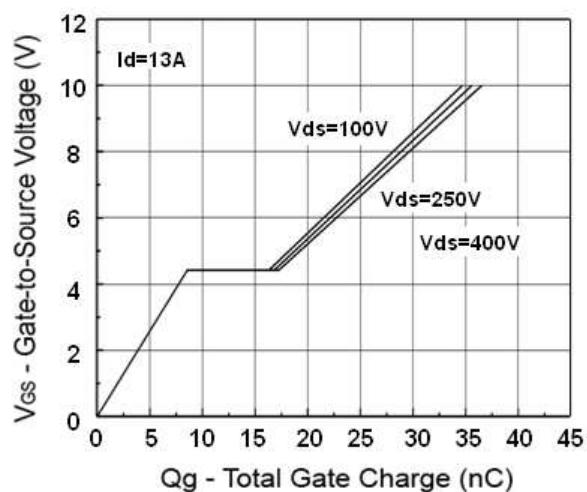
Transfer Characteristics



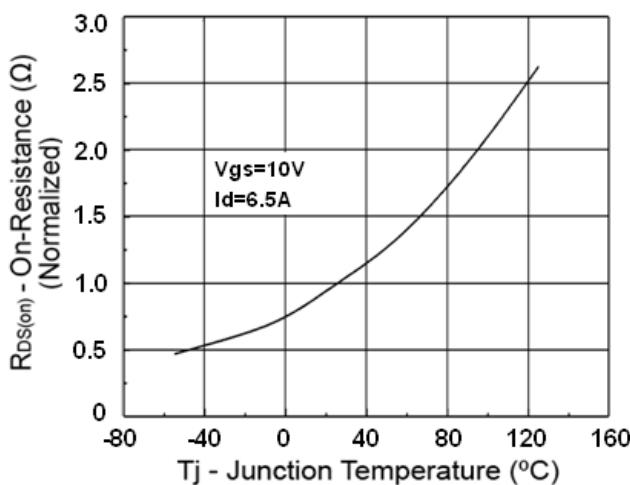
On-Resistance vs. Drain Current



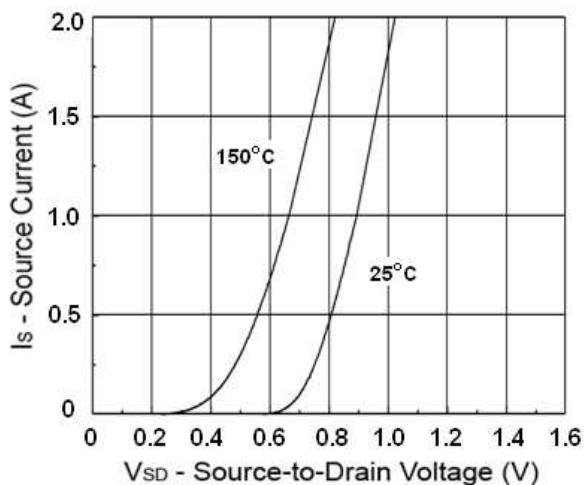
Gate Charge



On-Resistance vs. Junction Temperature

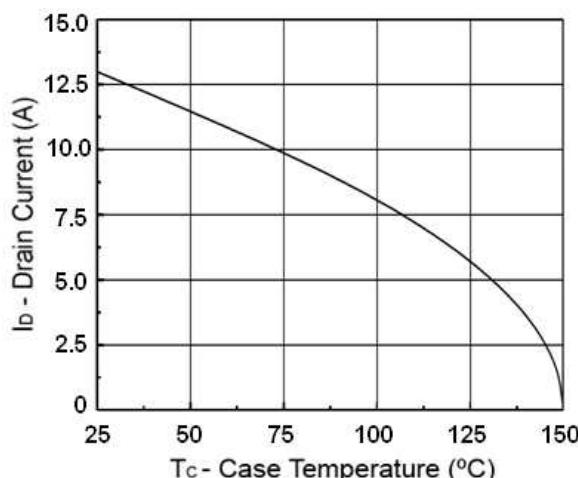


Source-Drain Diode Forward Voltage

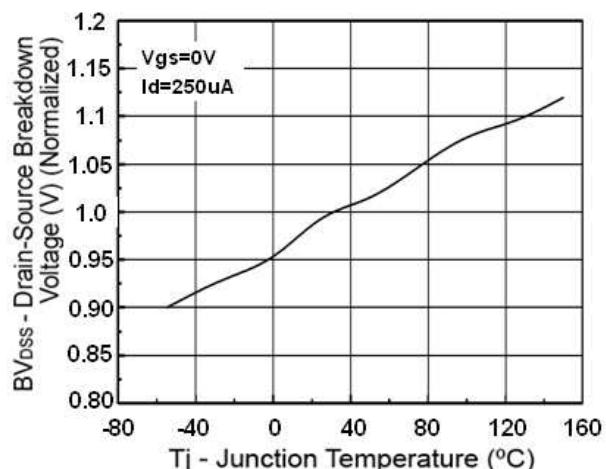


Electrical Characteristics Curve ($T_a = 25^\circ\text{C}$, unless otherwise noted)

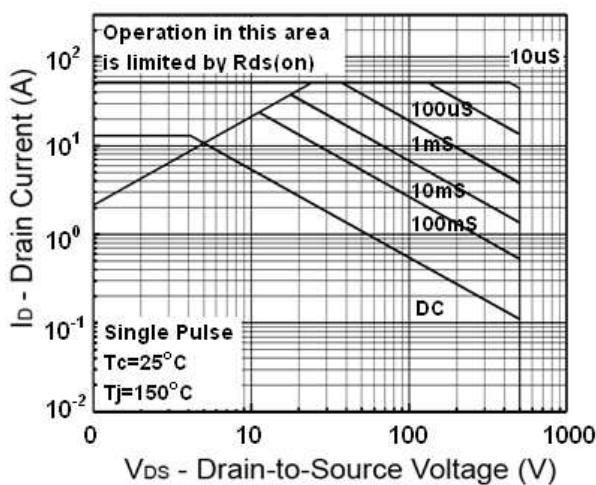
Drain Current vs. Case Temperature



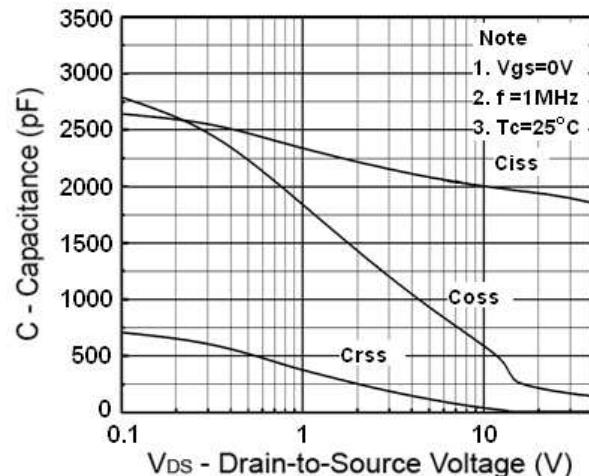
BV_{DSS} vs. Junction Temperature



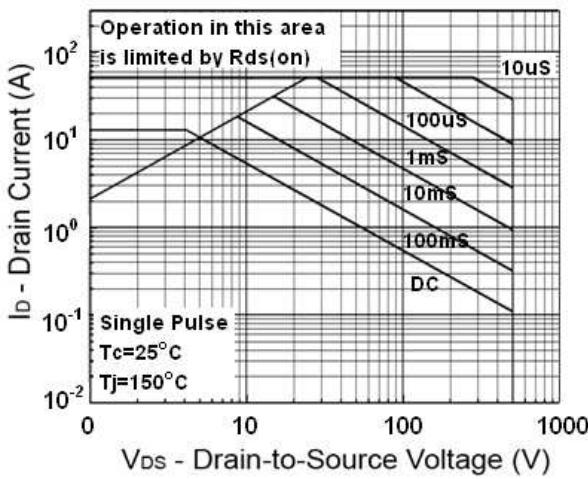
Maximum Safe Operating Area



Capacitance vs. Drain-Source Voltage

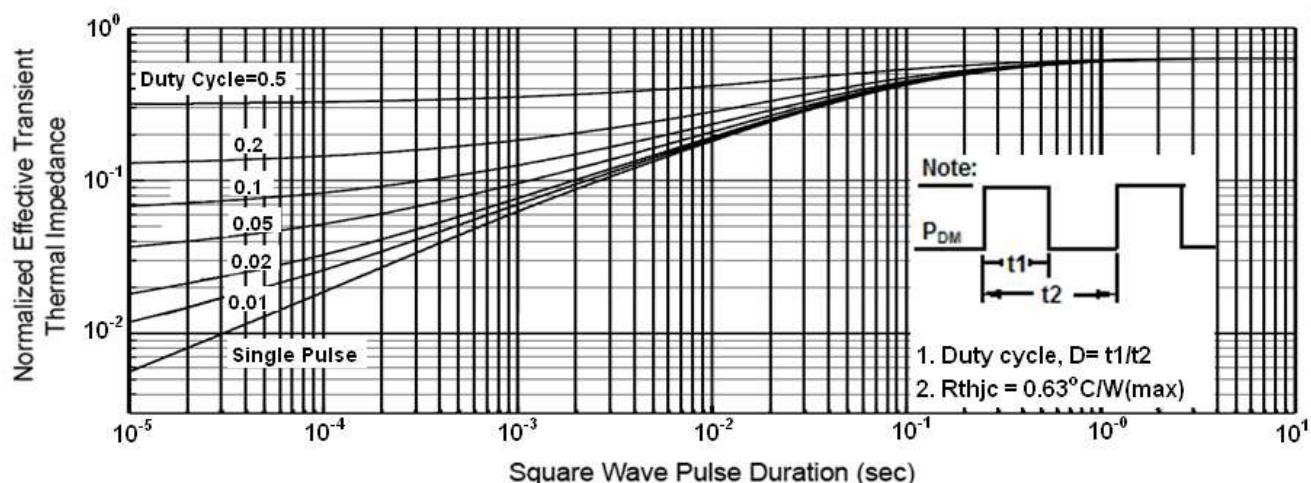


Maximum Safe Operating Area (ITO-220)

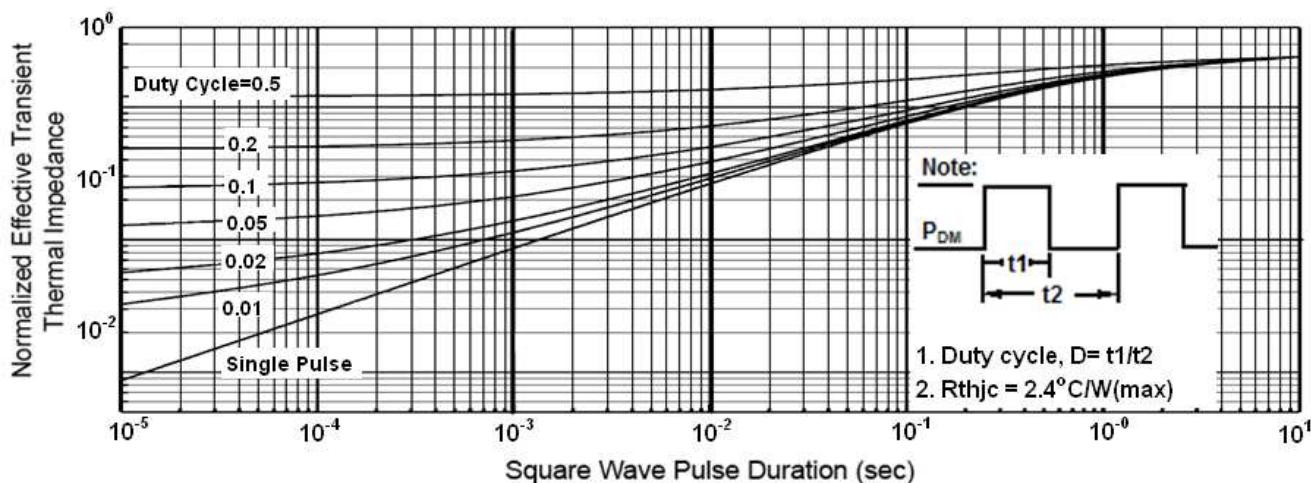


Electrical Characteristics Curve ($T_a = 25^\circ\text{C}$, unless otherwise noted)

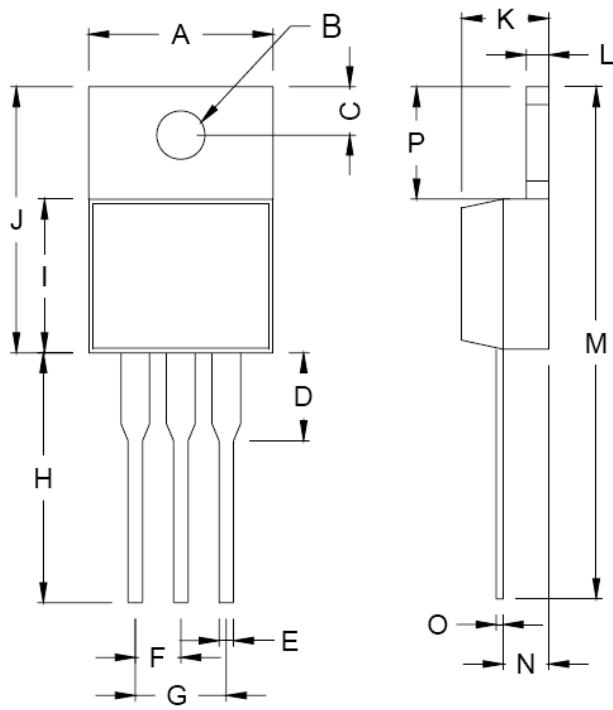
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient(ITO-220)

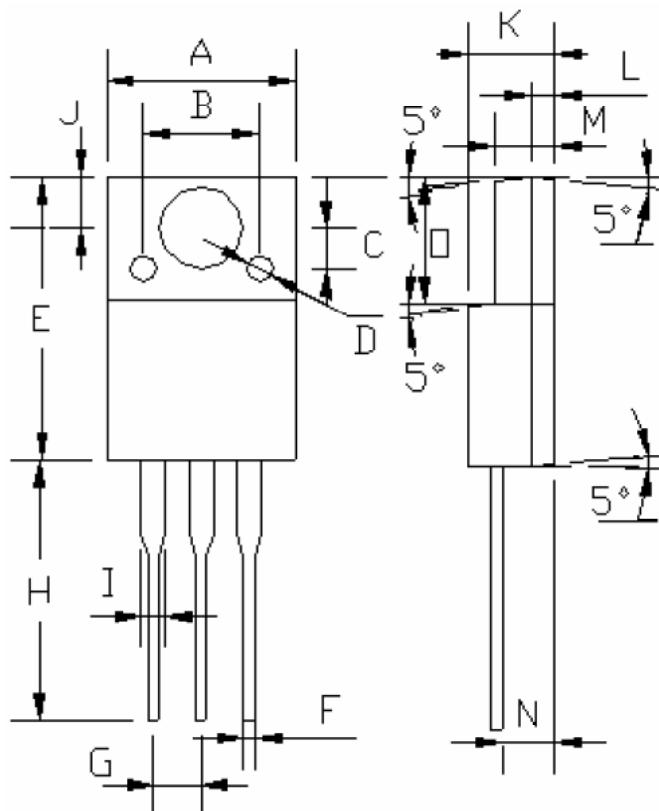


TO-220 Mechanical Drawing



TO-220 DIMENSION				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.00	10.50	0.394	0.413
B	3.74	3.91	0.147	0.154
C	2.44	2.94	0.096	0.116
D	--	6.35	--	0.250
E	0.38	1.10	0.015	0.043
F	2.34	2.71	0.092	0.107
G	4.69	5.43	0.185	0.214
H	12.70	14.73	0.500	0.580
I	8.38	9.38	0.330	0.369
J	14.22	16.51	0.560	0.650
K	3.55	4.82	0.140	0.190
L	1.16	1.40	0.046	0.055
M	27.70	29.62	1.091	1.166
N	2.03	2.92	0.080	0.115
O	0.25	0.61	0.010	0.024
P	5.84	6.85	0.230	0.270

ITO-220 Mechanical Drawing



ITO-220 DIMENSION				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.04	10.07	0.395	0.396
B	6.20 (typ.)		0.244 (typ.)	
C	2.20 (typ.)		0.087 (typ.)	
D	1.40 (typ.)		0.055 (typ.)	
E	15.0	15.20	0.591	0.598
F	0.52	0.54	0.020	0.021
G	2.35	2.73	0.093	0.107
H	13.50	13.55	0.531	0.533
I	1.11	1.49	0.044	0.058
J	2.60	2.80	0.102	0.110
K	4.49	4.50	0.176	0.177
L	1.15 (typ.)		0.045 (typ.)	
M	3.03	3.05	0.119	0.120
N	2.60	2.80	0.102	0.110
O	6.55	6.65	0.258	0.262

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